



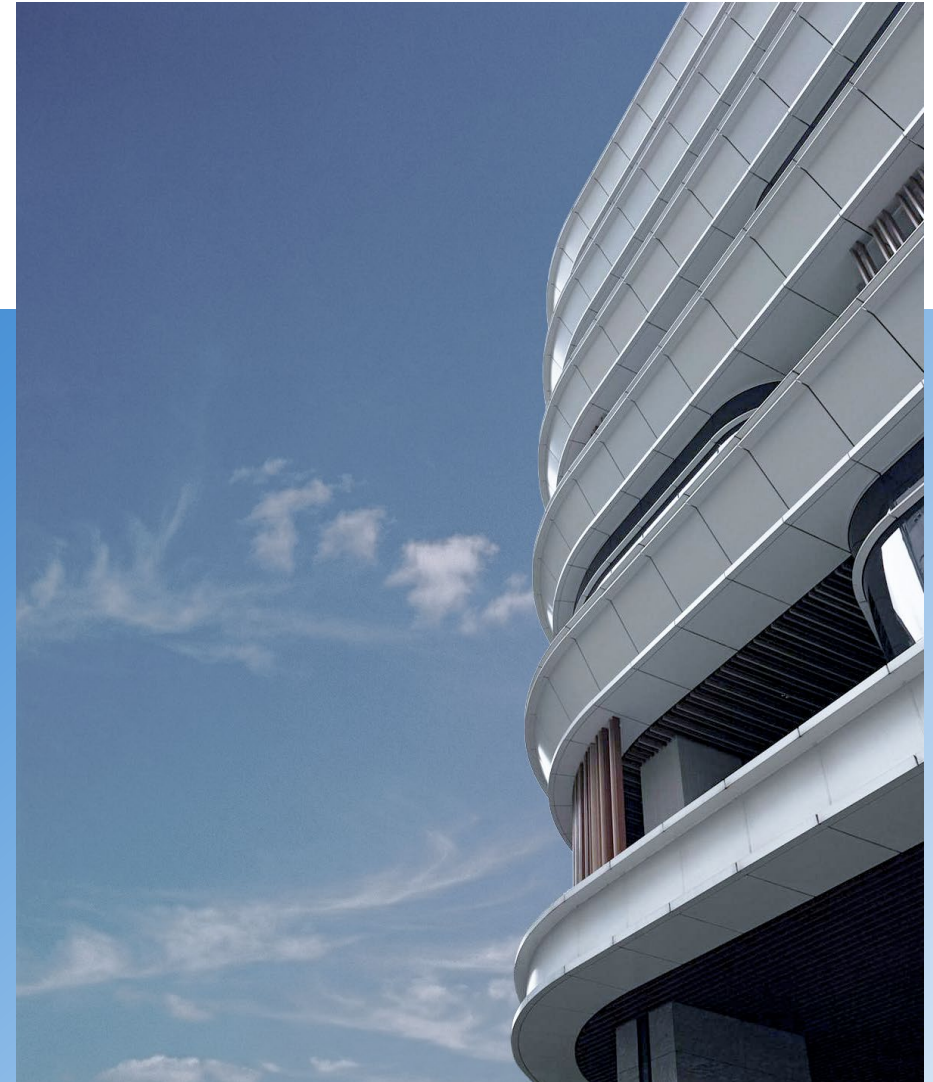
YOUR PROFESSIONAL PARTNER IN RFIC PACKAGE & FINAL TESTING



C O N T E N T S

01 Company Overview

02 Major Business Unit (GP)



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COMPANY OVERVIEW

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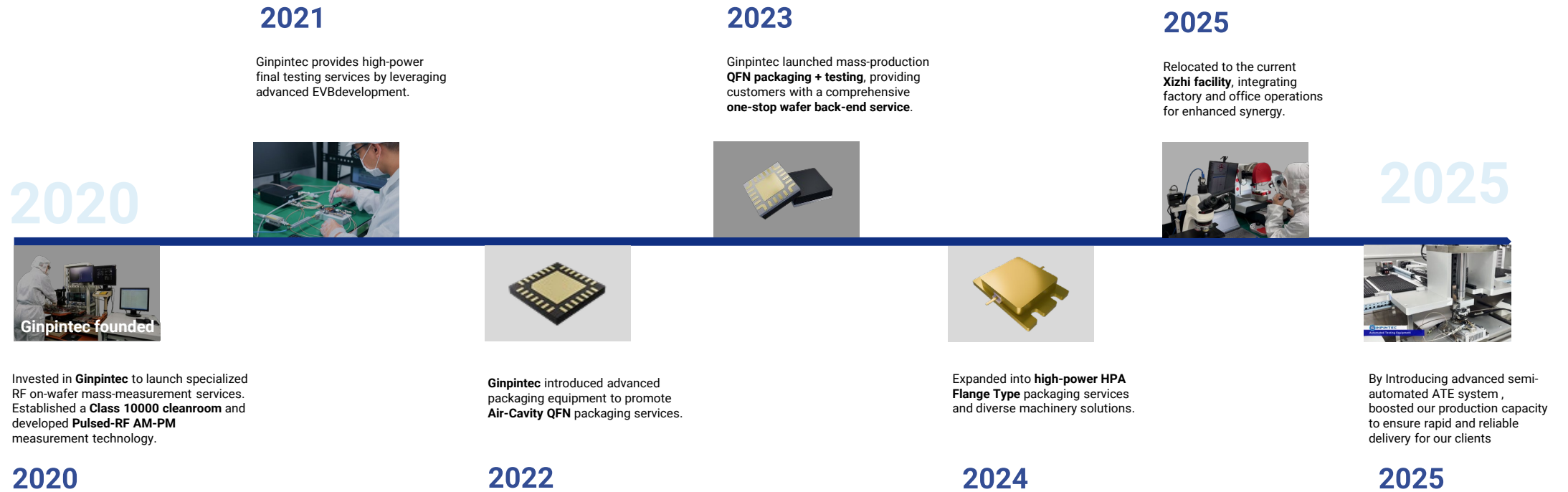
ROOTED IN RF TECHNOLOGY

Our Philosophy: Solid Integrity, Benevolent Service, and Relentless Excellence

Dedicated to treating clients with sincerity and serving with heart, we integrate RF technology and advanced engineering to pursue technical perfection and deliver the best customized solutions.



MILESTONES IN THE HISTORY OF GINPINTEC



OUR LABORATORY & OFFICE

Ginpintec Laboratory

- On Wafer Testing



Neihu District

Taipei Metropolitan Area

Neihu Xizhi

Honestco Office

- R&D
- Supply Management
- Sales
- Administration
- Purchasing
- QA
- Marketing



Xizhi District, Taiwan

Ginpintec Laboratory & Office

- Packaging
- Final Testing



Xizhi District, Taiwan

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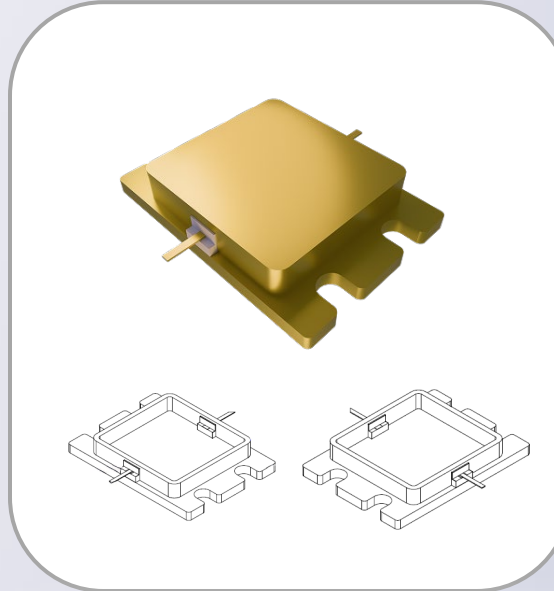
MAJOR BUSINESS UNIT





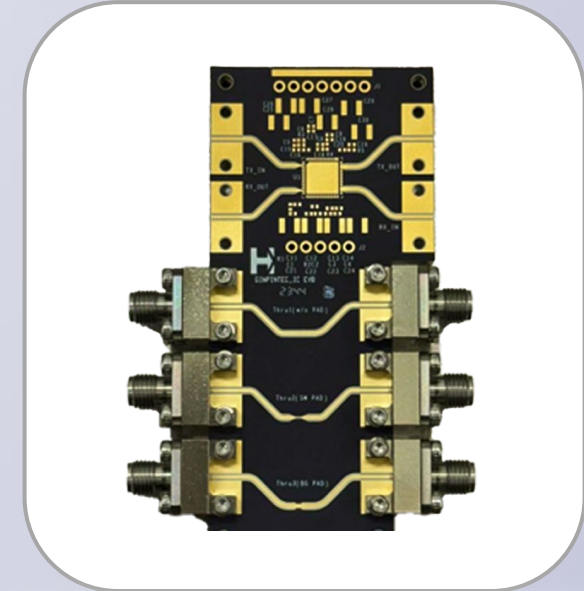
ON WAFER TESTING

- Quarter / Half wafers available
- Single / Multiple devices available
- 4-direction probing available
- 4-inch, 6-inch
- High-Power Pulse Measurement System up to 92GHz



PACKAGE

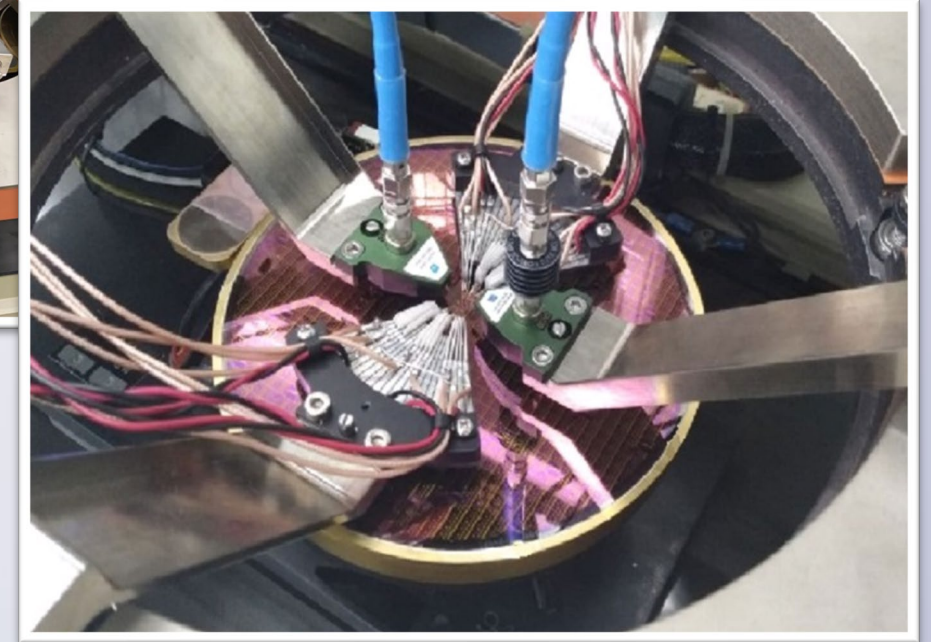
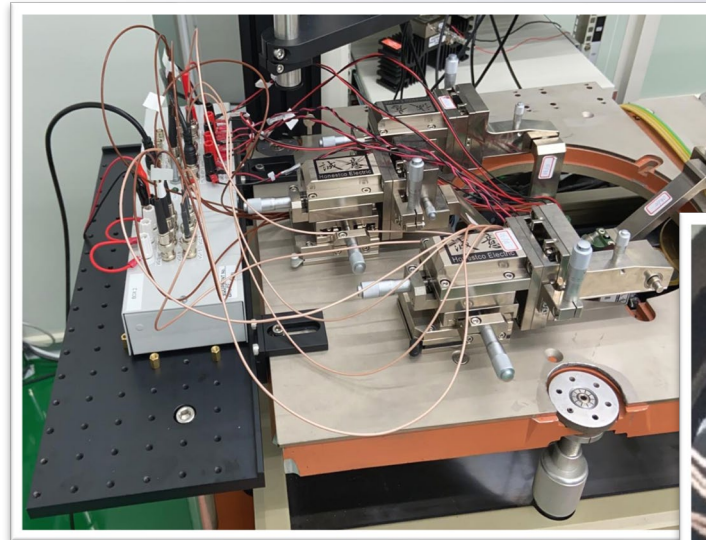
- Flip Chip Package
- High Power Package
- Air Cavity QFNs
- Overmold QFNs



FINAL TEST

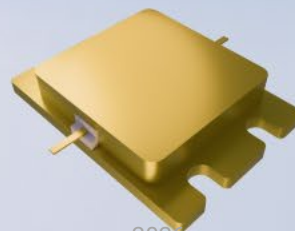
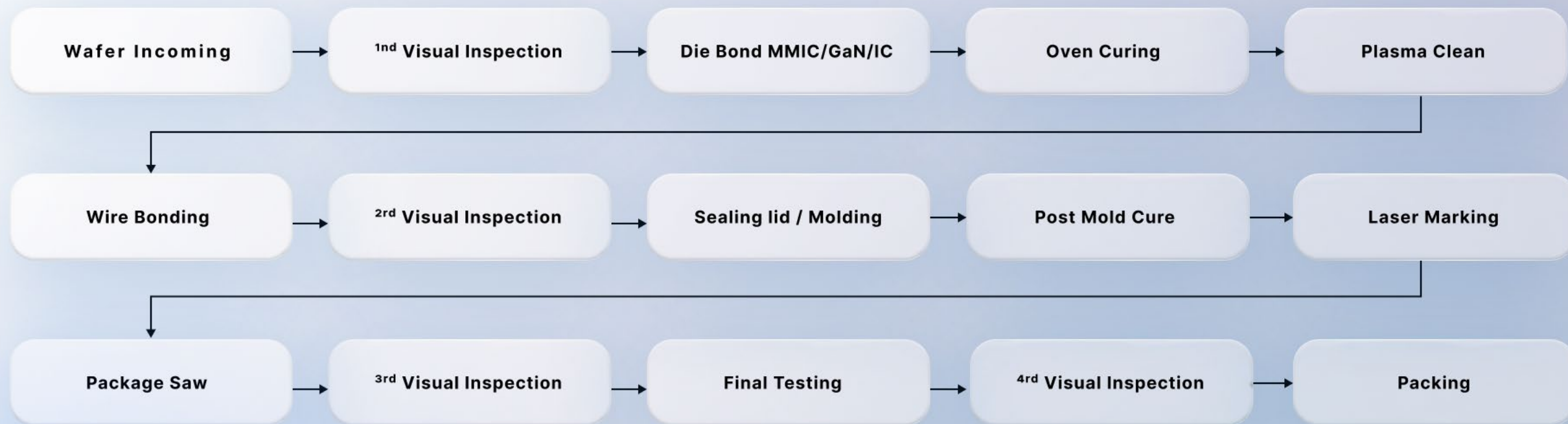
- In-House designed EVB and socket
- Chip-on-board Measurements
- High-Power Pulse Measurement System up to 92GHz
- @ duty cycle 5%

[RFOW] RF ON WAFER TESTING SYSTEM

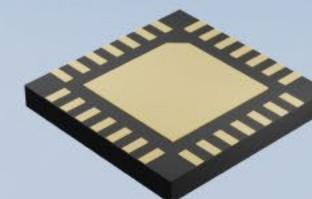
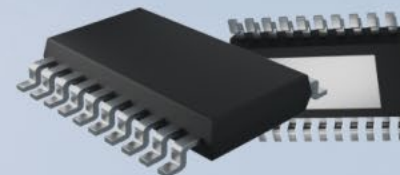


- Ginpintec measure service.
- 4 site probe measure.
- Typical RF probe*2.
- Customized DC probe*2.
- Production Measurement.
- Class 1000 clean room.
- DUT function: Power amplifier.





2026



SUCCESSFUL PROJECT REVIEW



1. Packaging and Final Testing(7×7 QFN 48L)

- 5.5 GHz, GaN, core chip
- HPA (47dBm) / LNA, 2 dies in single QFN.
- Overall FT yield > 95%.

2. Packaging and Final Testing(TSSOP20)

- 60W HPA, 2dies
- Final testing on-going

3. Packaging and Final Testing(Heat sink)

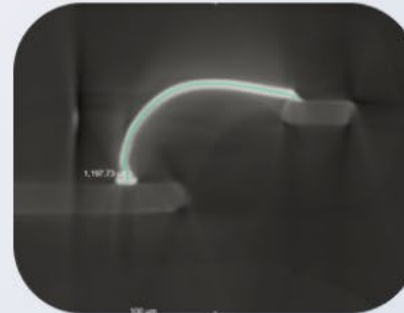
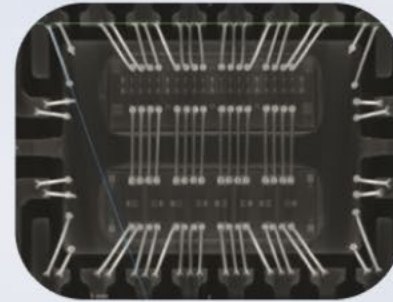
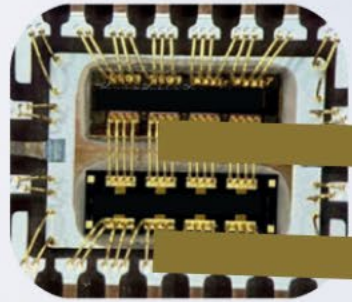
- 400W GaN HPA

PACKAGING AND FINAL TESTING (E-TSSOP20)

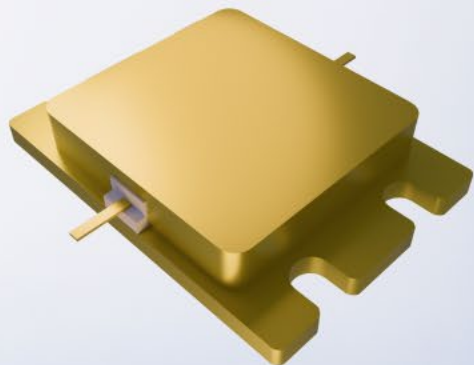


Package Type	20L e-TSSOP / 0.65 mm PITCH
Package Thickness	1.20 mm MAX
Die Type	GaAs (CAP) GaN (FET)
Die Size	1.0 x 3.0 (CAP) 0.95 x 3.0 (FET)
Die Thickness	4 mil
Mold Material	Sumitomo G700L Type Y-A
Die Attach Material	Sintered Ag, Namics H9890-10A
Wire	ø 2.0 mil / Au
MSL Rating	MSL 3
Status	Qualified, in MP

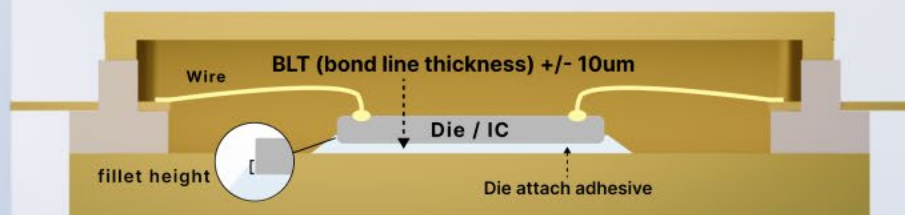
HPA for RADAR Application



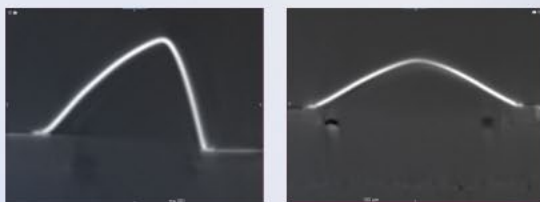
PACKAGING AND FINAL TESTING



BLT Control



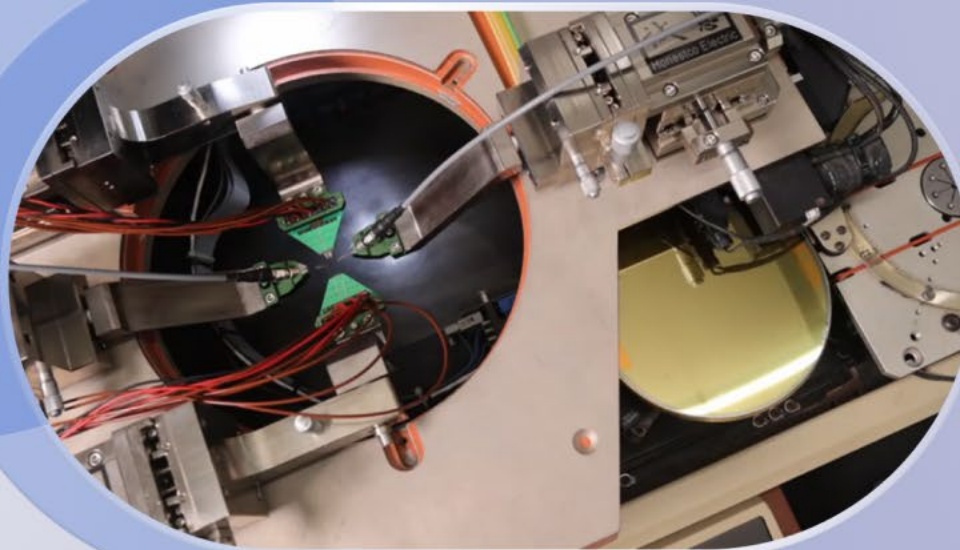
X-Ray



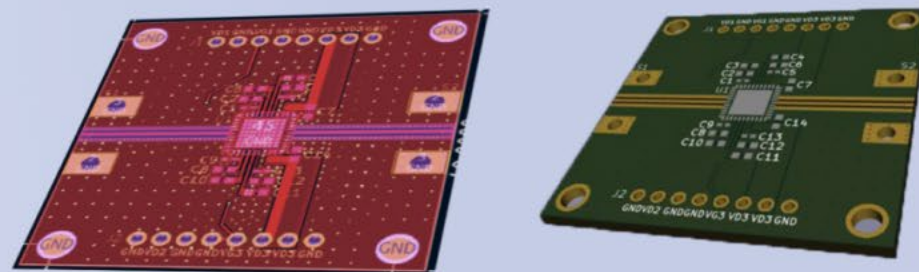
Wire Bonding



HIGH-POWER TX/RX MODULE AND AUTO-MEASURE SYSTEM

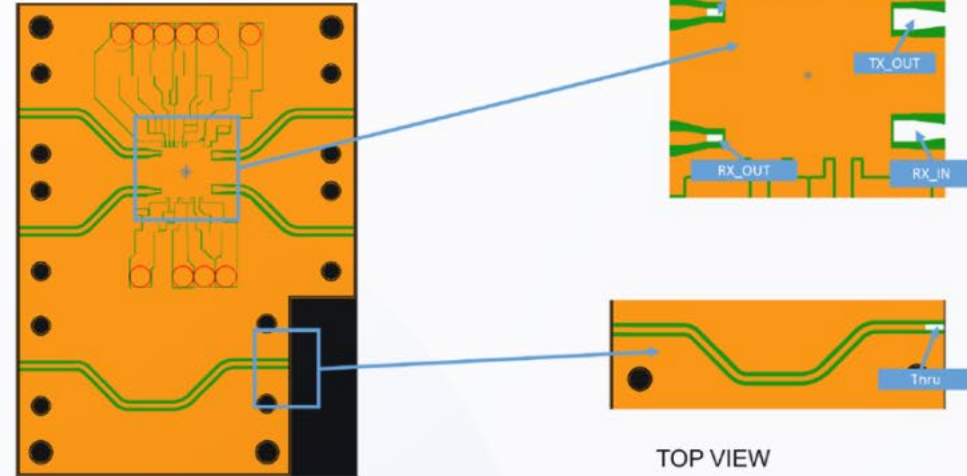


HIGH POWER PA EVB



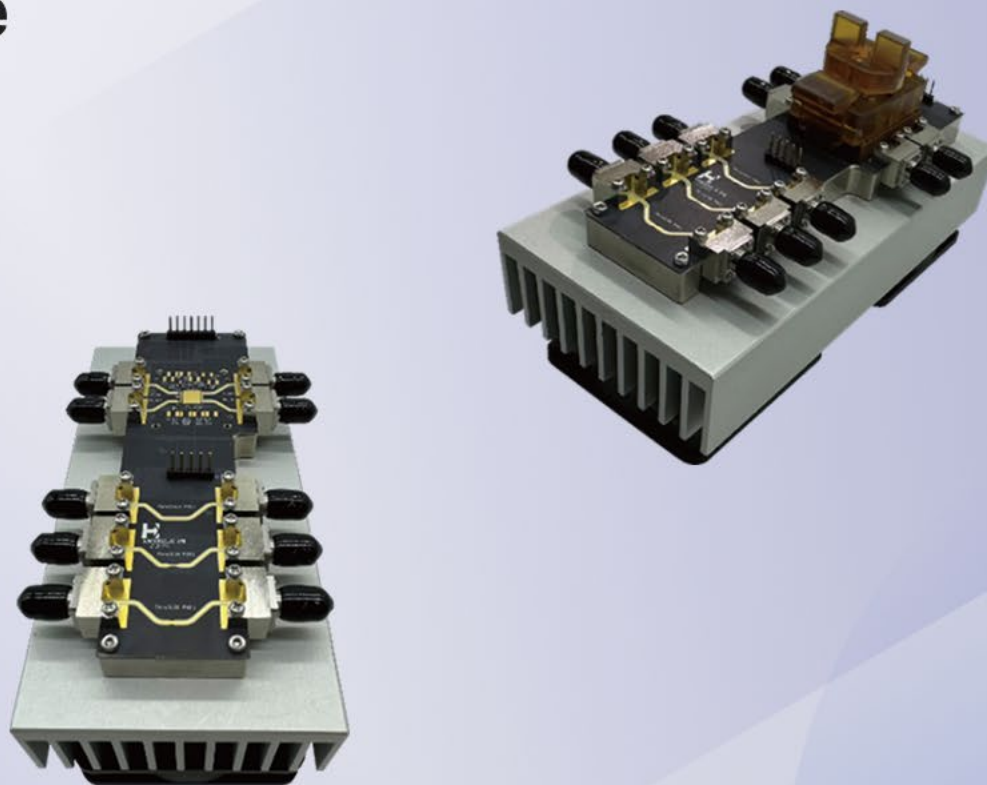
RF EVB DESIGN AND MANUFACTURING

Pin Define

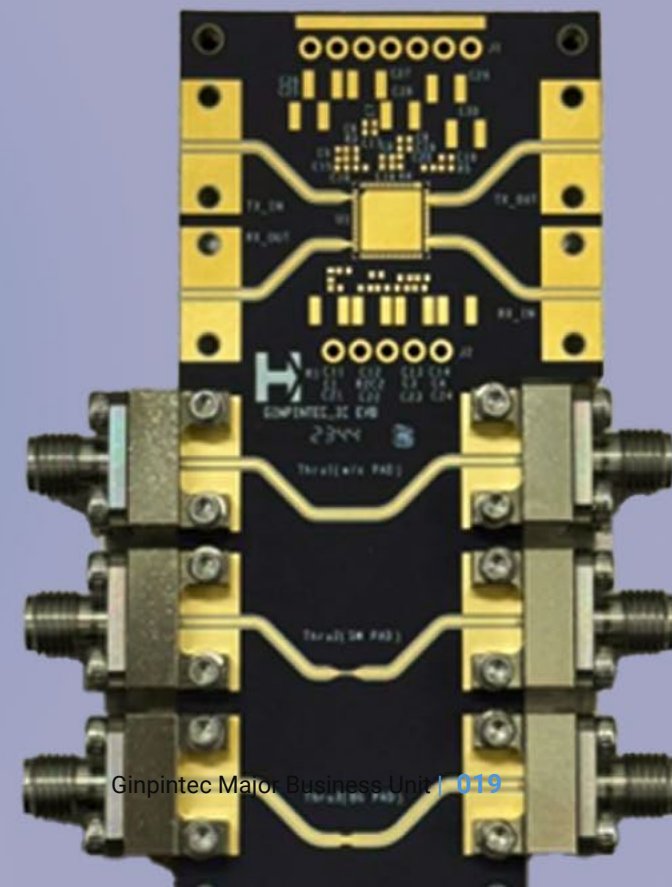


EVB

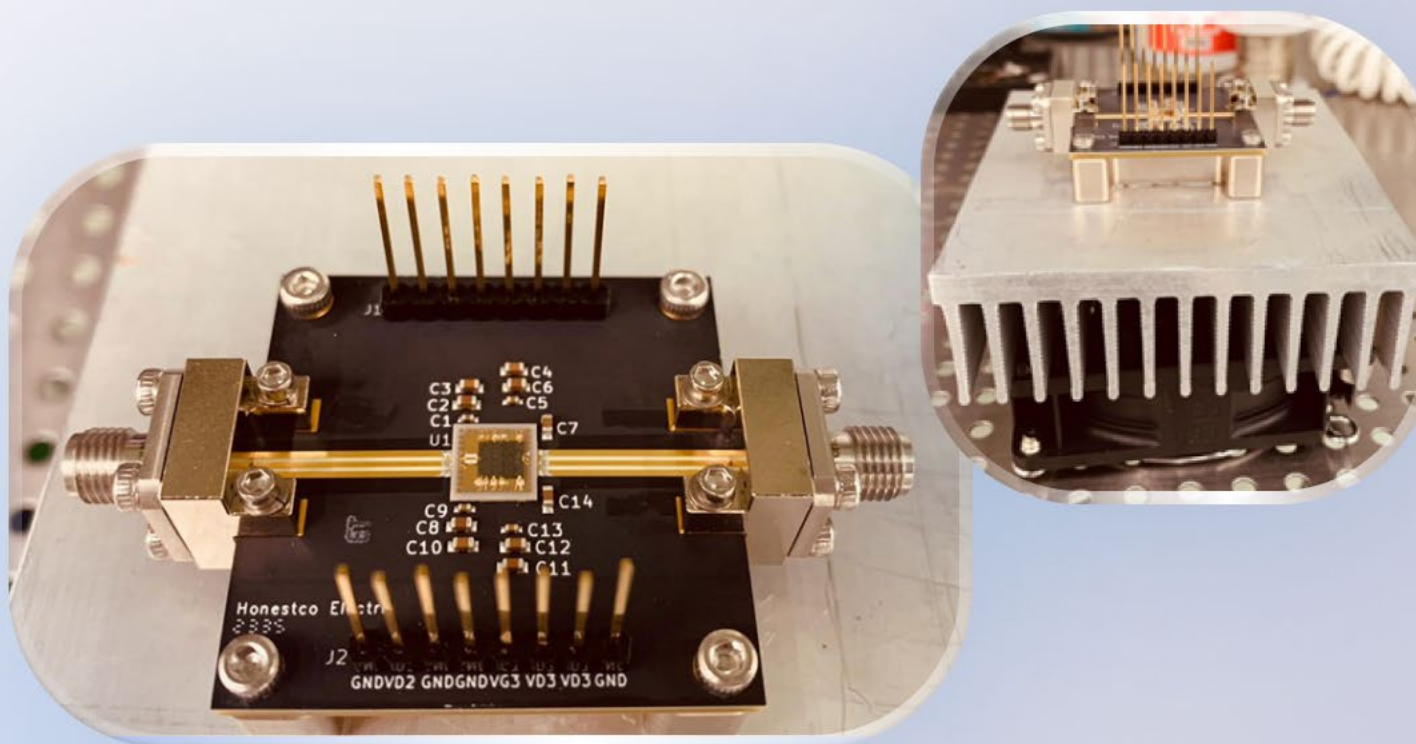
Module



EVB MODULE



HIGH POWER PA EVB MODULE





Thank You!